



FLX-2320R Equipment

Technical Specifications

Wafer stress testing equipment

1. Equipment hardware configuration

No.	Item	Specification	Description
1	Equipment Name	Wafer stress testing equipment	
2	Equipment Model	FLX-2320R	
3	wafer size	75-200mm wafers,	
4	Measurement range	1-4000Mpa (10000A thin film, wafer thickness 725um)	
5	temperature	room temperature	
6	Transmission method	Manual	Manual wafer handling
7	Drawing methods	automatic	
8	Scan range	200mm	
9	Scanning accuracy	0.01mm	0.02mm
10	Measurement reproducibility	1.3 MPa (1 sig)	Standard slice calculation (previous value x5 + subsequent value x5)
11	Computer System	1. Intel dual-core 64 -bit processor, Windows 10 operating system . 3.6GHz processor, 16GB RAM, 1TB hard drive 2. >17-inch LCD monitor and mouse/keyboard	Windows 11 operating system
12	Image processing	1. Features two-dimensional image display. 2. It has 3D mapping capabilities.	

13	Operating software	1. Possesses data management and storage functions. 2. Supports English user interface 3. Has three levels of management authority. 4. Includes equipment alarm records and operation records. 5. Program size ≥ 3	
14	Calibration tools	Standard calibration tools and samples are provided *1	Provide calibration films
15	Attachment Tools	One set of maintenance tools will be provided .	No maintenance tools
16	Manual (English version)	1. User Manual *1 2. A maintenance manual will be provided . 3. Repair Manual *1 4. Provide a spare parts list	

2. Equipment System Requirements

Serial Number	content	Test Standards	Specification		unit
			Require	Supplier confirmation	
1	Equipment Dependent Uptime(%;Average) Effective working time of equipment	Based on real data .	≥95		%
2	Mean Time Between Failure (MTBF) Mean time between failures	Based on real data .	>350		Hours
3	Mean Time to Repair (MTTR) Mean time between repairs	Based on real data .	<4		Hours
4	Wafer breakage (chip fragmentation)	By wafer counter based on wafer count	≤1/10000		pcs

follow SEMI standard, time is calculated in months.

3. Process Specifications

Serial Number	project	Specification
1	Measurement accuracy	2MPa or 2.5% 2.5% standard sample calculation (previous value x5 times + subsequent value x5 times)
2	Measurement reproducibility	1.3 MPa. Standard slice calculation (previous value x5 + subsequent value x5)